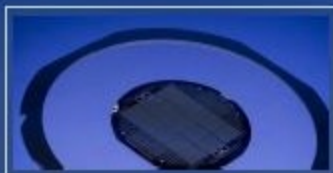


CONTRACT PACKAGE DESIGN AND ASSEMBLY SERVICES



- MPW
- MEMS
- GaAs
- Laminate
- Glass

Optoelectronic & Photonic Packaging
Optical Modelling



- Space & Military
- Harsh Environment
- Fast Prototyping
- FM Parts

Laser Diode Packaging
UV to IR



- LED
- Chip on Board
- CPV
- Flip-Chip

